

Certificate of non-use of The Controlled Substances

Company name Littelfuse, Inc.

Product Covered Thyristor, TO-92 Package

SIDAC, TO-92 Package SIDACtor® TO-92 Package

Issue Date August 8, 2012

It is hereby certified by Littelfuse, Inc., that there is neither RoHS (EU Directive 2011/65/EU)-restricted substance, nor such use, for materials to be used for unit parts, for packing/packaging materials, and for additives and the like in the manufacturing processes.

It is also certified by Littelfuse, Inc., that the products listed in this report do not contain Halogens and their compounds judged per widely accepted industrial guidelines.

In addition, it is hereby reported to you that the parts and sub-materials, the materials to be used for unit parts, the packing/packaging materials, and the additives and the like in the manufacturing processes, are all composed of the following components.

Issued by			

< K. Yoshimoto, Senior Product Engineer, Littelfuse, Inc.>

(1) Parts, sub-materials and unit parts

This document covers TO-92 RoHS-Compliant products series supplied by Littelfuse, Inc. Please see page 2-4 for the complete list of part number covered by this report.

- < Homogeneous Materials used >
 Please see figure and table 1 on page 5 and table 2 on page 6 of this document.
- (2) The analytical data on all measurable substances

 Please see annex 1 through 6, attached to this document

Remarks:

1. Pb (lead) contained in die bonding solder (item 7 on page 5) and passivation glass (item 6) to be categorized as exempt in RoHS Annex III 7(a) and 7(c)-I.

Please refer to Annex 7 of this report for the extract of the applicable exemptions of RoHS (EU Directive 2011/65/EU)

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Littelfuse Part Number covered by this report

TO-92 products supplied by Littelfuse are categorized into two groups, 3-leaded TO-92 and 2-leaded TO-92.

All products use the same raw materials and all products listed in this report meet RoHS requirement by using lead (Pb) exemptions, as well as Halogen-free requirement,.

Please follow table below to locate specific part number.

Group #	Package	Generic Description	P/N table
1	TO-92 (3-leaded)	Thyristor 2Nxxxx EC103xx LxxxEx QxxxEx SxxxEx TCR22-xx	See page 3
2	TO-92 (2-leaded)	SIDAC KxxxxE70 SIDACtor PxxxxEAL PxxxxEBL PxxxxECL	See page 4

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GROUP 1: TO-92 Three-leaded

Standard (Catalog) Part Number			SPECIAL	
2N5060	EC103D	L401E3	Q4X8E3	DEVICE P/N
2N5061	EC103D1	L401E5	Q4X8E4	
2N5062	EC103D2	L401E6	Q501E3	Any Special P/N that has base
2N5063	EC103D3	L401E8	Q501E4	standard P/N listed in this table
2N5064	EC103E	L4X8E3	Q601E3	III tillo table
2N6504	EC103E1	L4X8E5	Q601E4	
2N6505	EC103E2	L4X8E6	Q6X8E3	
2N6506	EC103E3	L4X8E8	Q6X8E4	
2N6507	EC103M	L501E3		
2N6508	EC103M1	L501E5	S031E	
2N6564	EC103M2	L601E3	S051E	OPTIONAL
2N6565	EC103M3	L601E5	S101E	SUFFIX
	EC103Y	L601E6	S201E	Any Part Number
EC103A	EC103Y1	L601E8	S401E	listed here may be followed by suffix
EC103A1	EC103Y2	L6X8E3	S601E	for packing
EC103A2	EC103Y3	L6X8E5		options, such as "RP" or "AP", or
EC103A3		L6X8E6	TCR22-2	lead form options such as "73", "75",
EC103B	L201E3	L6X8E8	TCR22-3	etc.
EC103B1	L201E5		TCR22-4	
EC103B2	L201E6	Q201E3	TCR22-6	
EC103B3	L201E8	Q201E4	TCR22-8	
EC103C	L2X8E3	Q2X8E3		
EC103C1	L2X8E5	Q2X8E4		
EC103C2	L2X8E6	Q401E3		
EC103C3	L2X8E8	Q401E4		

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GROUP 2: TO-92 Two-leaded

Standard (C	Catalog) Part Number	SPECIAL DEVICE P/N
K0900E70	P0900ECL	Any Special P/N which has
K1050E70	P0900ECMCL	base standard P/N listed in
K1100E70	P1100EAL	this table.
K1200E70	P1100EBL	P637P2600EB
K1300E70	P1100ECL	P693P3100EC
K1400E70	P1100ECMCL	P694P3100EC
K1500E70	P1300EAL	
K2000E70	P1300EBL	
K2000EH70	P1300ECL	
K2200E70	P1300ECMCL	
K2200EH70	P1500EAL	
K2400E70	P1500EBL	
K2400EH70	P1500ECL	
K2500E70	P1500ECMCL	
K2500EH70	P1800EAL	
	P1800EBL	
P0080EAL	P1800ECL	
P0080EAMCL	P1800ECMCL	
P0080EBL	P2300EAL	
P0080EBMCL	P2300EBL	
P0080ECL	P2300ECL	
P0080ECMCL	P2300ECMCL	
P0300EAL	P2600EAL	
P0300EAMCL	P2600EBL	
P0300EBL	P2600ECL	
P0300EBMCL	P2600ECMCL	
P0300ECL	P3100EAL	
P0300ECMCL	P3100EBL	
P0640EAL	P3100ECL	
P0640EBL	P3100ECMCL	
P0640ECL	P3500EAL	
P0640ECMCL	P3500EBL	
P0720EAL	P3500ECL	
P0720EBL	P3500ECMCL	
P0720ECMCL		
P0720EC		П
P0900EAL		nber listed here may be followed by s, such as RP, RP1, RP2, RP3 or AP.
P0900EBL	Sum to packing options	5, 54611 45 TXI , IXI 1, IXI 2, IXI 5 01 AF.

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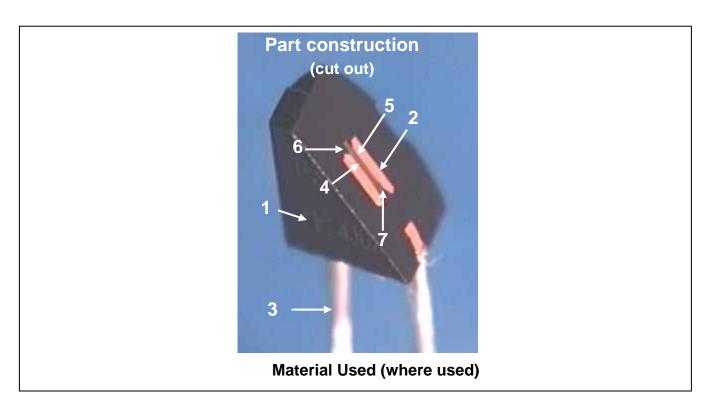


Table 1: Homogeneous Material Used

#	Description	Name of Material	Туре	Analysis data
1	Molding compound	epoxy resin	plastic	annex 1
2	Lead frame	copper alloy	metal	annex 2 & 2A (two materials used)
3	Lead finish	tin alloy	metal	annex 3
4	Silicon die	silicon	metal	anney 4 tooted as Niekel plated water
5	Nickel electrode	nickel	metal	annex 4, tested as Nickel-plated wafer.
6	Passivation glass	glass	glass	annex 5. Pb in this glass is exempted by RoHS Annex III 7(c)-I.
7	Die bonding solder	solder	metal	annex 6. Pb in this solder is exempted by RoHS Annex III 7(a).

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Table 2: RoHS-regulated substance in raw materials

Components				Analysi	s Resul	t		
	Cd Cadmium	Cr Chromium	Hg Mercury	Pb Lead	PBB & PBDE	Halogen (Total)	Phthalates	HBCD
As Component Total (Typical Value)	< 2ppm	< 2ppm	< 2ppm	<10 ppm* ¹ (1.9% ²)	< 5ppm	< 50ppm	< 100ppm	< 10ppm
Molding compound (mixture of phenolix resin, epoxy resin, filler and non-brominated fire retardant) See Annex 1 for the detail.	< 2ppm	< 1ppm	< 2ppm	< 2ppm	< 5ppm	<50ppm	< 100ppm	< 10ppm
Lead frame (Copper Alloy KFC or C194) See Annex 2 & 2A for the detail.	< 2ppm	< 2ppm	< 2ppm	18ppm *3	< 5ppm			
Outside lead finish (Matte-Tin plating) See Annex 3 for the detail.	< 2ppm	< 2ppm	< 2ppm	20ppm *3	< 5ppm			
Silicon Die (Silicon + Ni electrode) See Annex 4 for the detail	< 2ppm	< 1ppm	< 2ppm	31ppm *3	< 5ppm			
Passivation Glass See Annex 5 for the detail.	< 2ppm	< 1ppm	< 2ppm	41% ^{*4}	< 5ppm	< 50ppm		
Die Bonding Solder (Pb/Sn/Ag=88/10/2) See Annex 6 for the detail	< 2ppm	< 2ppm	< 2ppm	88 wt% *5	< 5ppm	< 50ppm	< 30ppm	< 10ppm

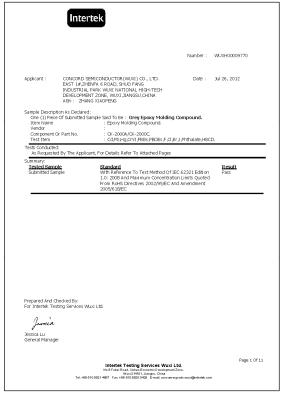
- *1 Less than 10ppm Pb content overall, <u>excluding</u> Pb from the die bonding solder and the passivation glass on the silicon die.
- *2 Maximum 1.9wt% or 3.2mg of Pb (lead) content overall, including the RoHS-exempted use of Pb
- *3 Pb (lead) contained in lead frame, outside finish and silicon wafer is <u>not</u> exempted from restriction by RoHS, but considered as process contamination. Littelfuse does not add Pb (lead) intentionally.
- *4 Pb (lead) contained in passivation glass is exempted from restriction by RoHS Annex III 7(c)-I.
- *5 Pb (lead) contained in die bonding solder is exempted from restriction by RoHS Annex III 7(a).

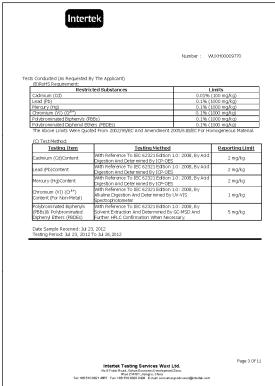
Please refer to Annex 7 of this report for the applicable exemptions of RoHS (EU Directive 2011/65/EU)

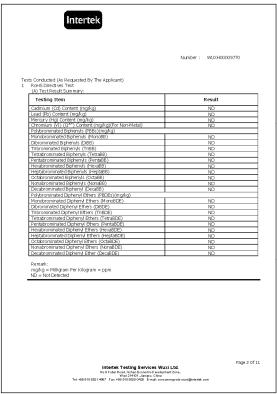
August 8, 2012 Littelfuse, Inc. Page 6 of 6

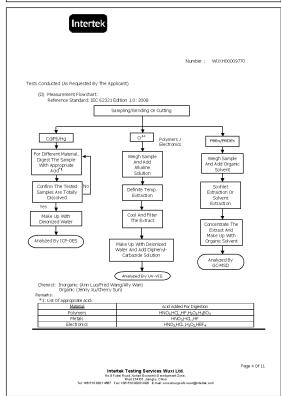


Annex 1: Analysis Result of Molding Compound (Page 1-4 of 11)



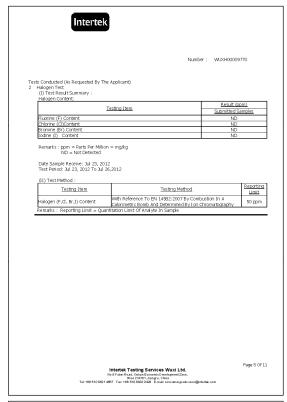


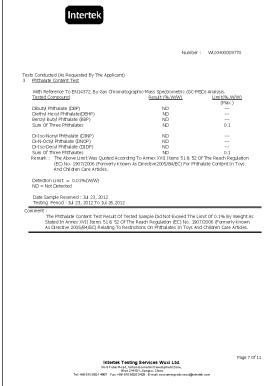


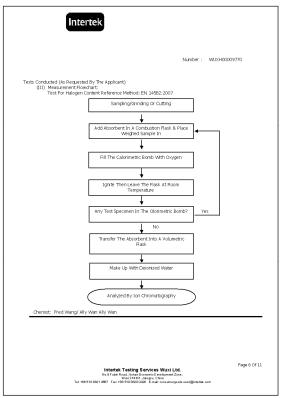


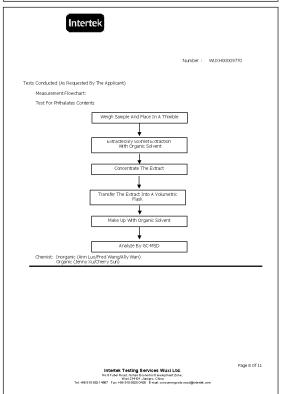


Annex 1: Analysis Result of Molding Compound (Page 5-8 of 11)



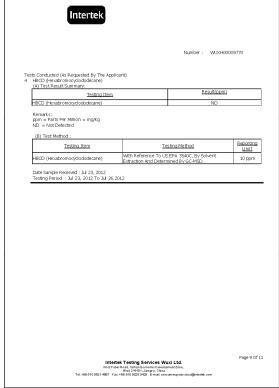


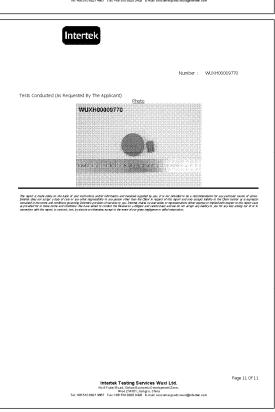


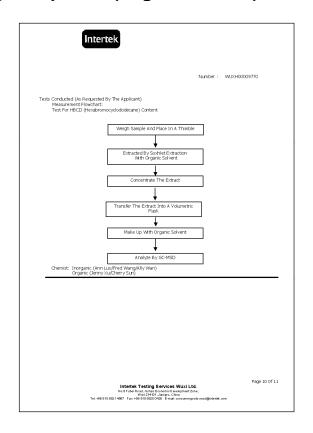




Annex 1: Analysis Result of Molding Compound (Page 9-11 of 11)



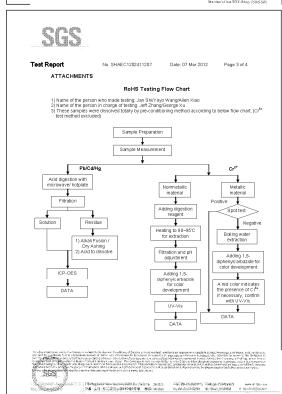


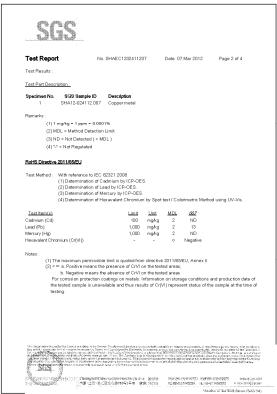


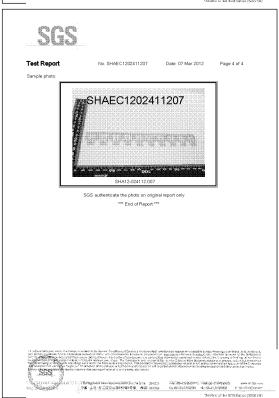


Annex 2: Analysis Result of Lead frame (KFC, Page 1-4 of 4)







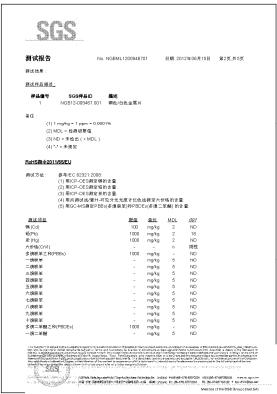


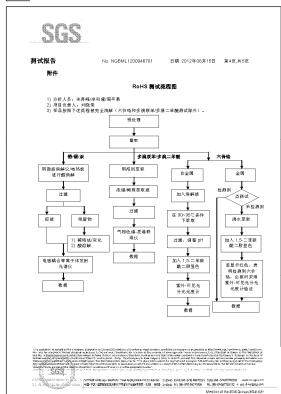


Annex 2A: Analysis Result of Lead frame (C194, Page 1-4 of 5)











Annex 2A: Analysis Result of Lead frame (C194, Page 5 of 5)

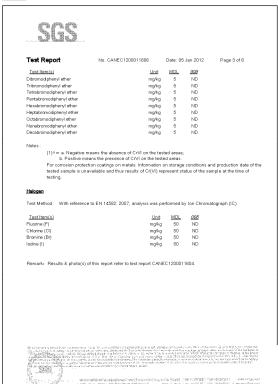


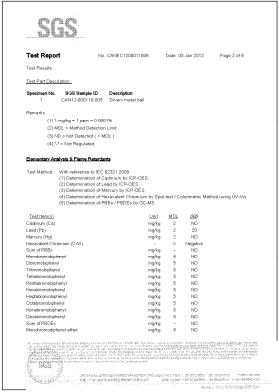
August 8, 2012 Littelfuse, Inc. Annex 2A-2

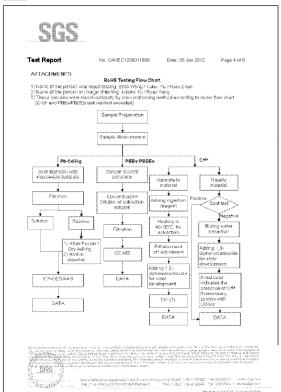


Annex 3: Analysis Result of Lead finish (page 1-4 of 6)



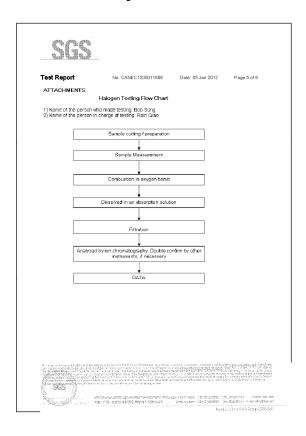


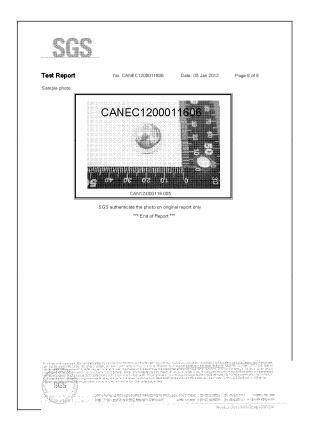






Annex 3: Analysis Result of Lead finish (page 5-6 of 6)

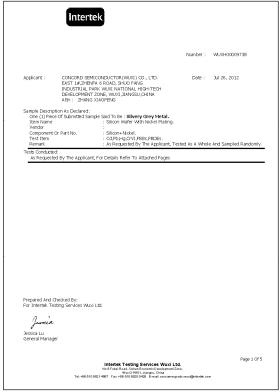


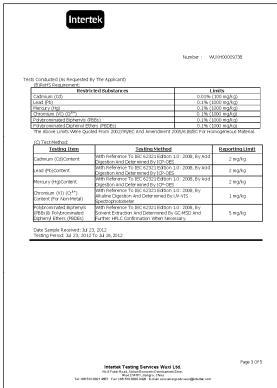


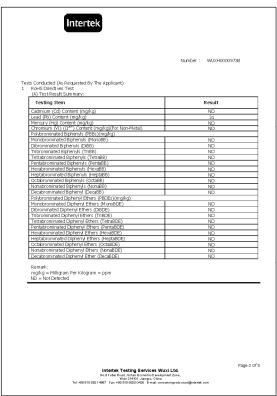
August 8, 2012 Littelfuse, Inc. Annex 3-2

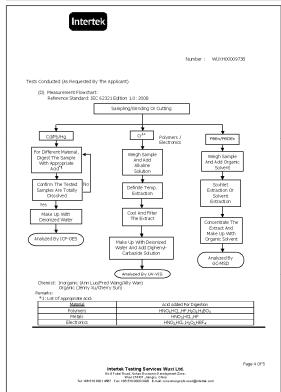


Annex 4: Analysis Result of Ni-plated Wafer (Page 1-4 of 5)



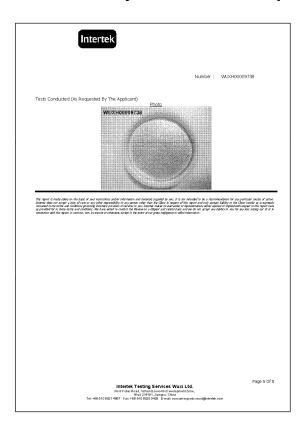








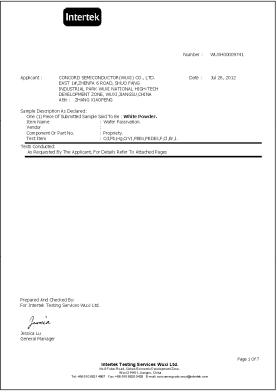
Annex 4: Analysis Result of Ni-plated Wafer (Page 5 of 5)

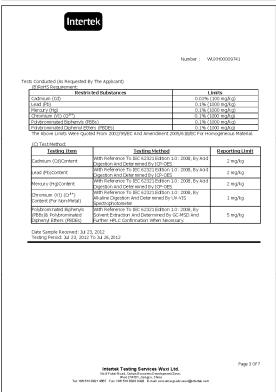


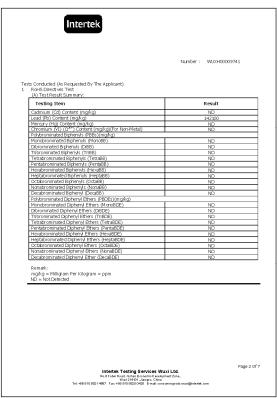
August 8, 2012 Littelfuse, Inc. Annex 4-2

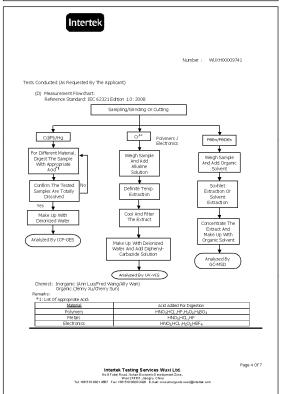


Annex 5: Analysis Result of Passivation Glass (Page 1-4 of 7)



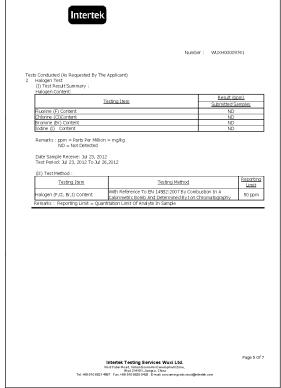


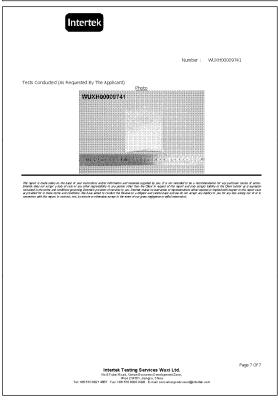


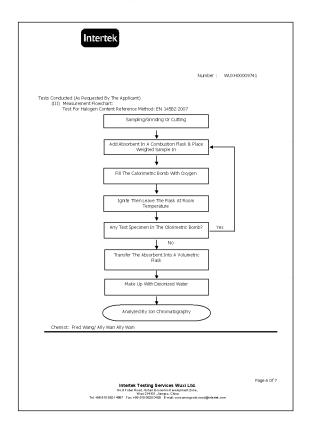




Annex 5: Analysis Result of Passivation Glass (Page 5-7 of 7)



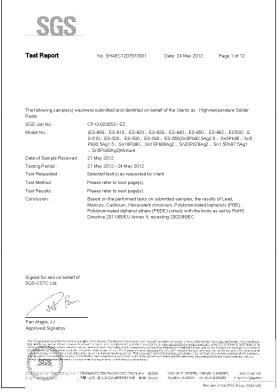


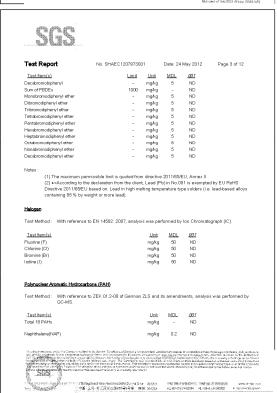


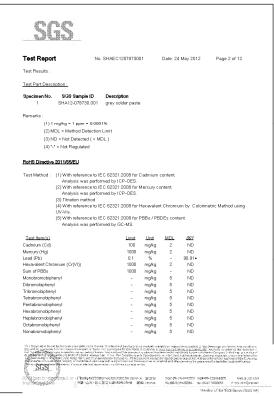
August 8, 2012 Littelfuse, Inc. Annex 5-2

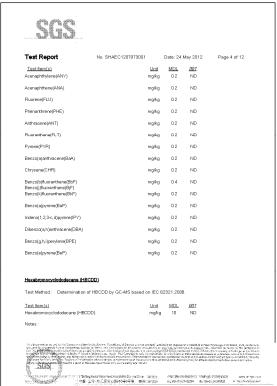


Annex 6: Analysis Result of Die Bonding Solder (Page 1-4 of 12)



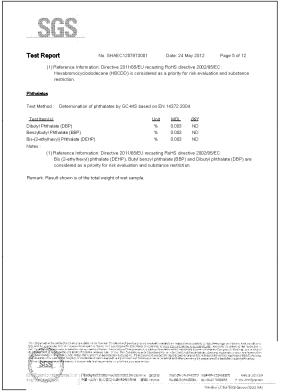


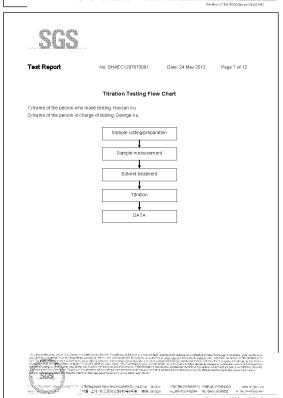


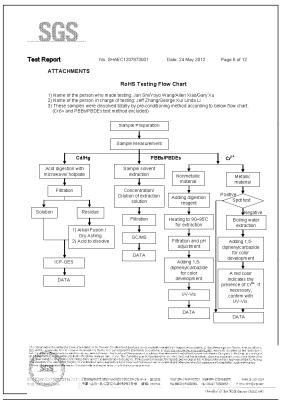


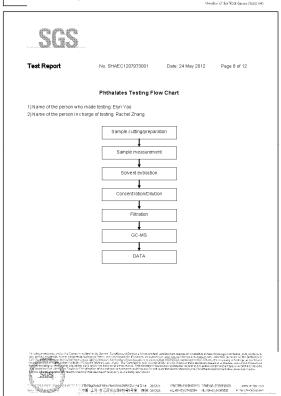


Annex 6: Analysis Result of Die Bonding Solder (Page 5-8 of 12)



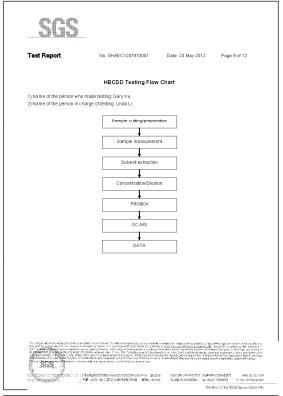


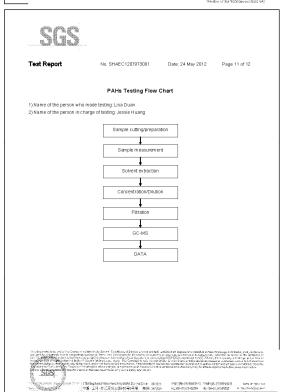


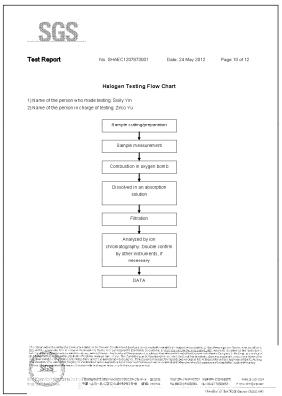


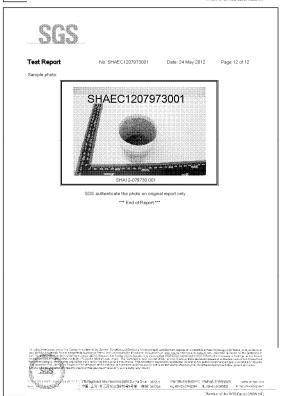


Annex 6: Analysis Result of Die Bonding Solder (Page 9-12 of 12)



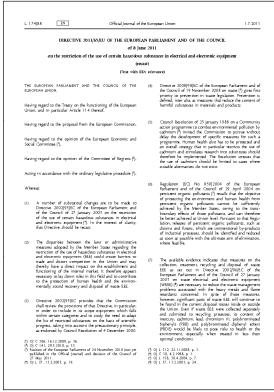








Annex 7: Applicable RoHS exemptions (2011/65/EU Annex III)



		tion of 4 December 2000.	optimal conditions.	prominated diphenyl ether pose risks to health or the when treated in less that
(*) Fosition o published 27 May 2 (*) OJ L 37,	f the European Parliament of in the Official Journal) and 011. 13.2.2003, p. 19.	f 24 November 2010 (not yet I decision of the Council of	(% O) L 312, 22.11.2008, p. 3. (% O) C 30, 4.2.1988, p. 1. (% O) L 158, 10.4.2004, p. 7. (% O) L 37, 13.2.2003, p. 24.	
L 174/100	EN	Official Journal of th	he European Union	1.7.201
		ANN	ex m	
	Restricted substances se	ferred to in Article 4(1) and r homogeneou	nasimem concentration values tolera as materials	ed by weight in
	Lead (0,1 %)			
	Mercury (0.1 %)			
	Cadmium (0,01 %) Hexavalent chromium (0,1	90		
	Polybrominated biphenyls			
	Polybrominated diphenyl e			
		_	_	

1.7.2011 EN Official Journal of the	he European Union L 174/9
3. Paragraph I shall apply to medical devices and monitoring and control instruments which are placed on the market from 25 July 2014, or in two dupmosin residual devices which are placed on the market from 22 July 2016 and to industrial monitoring and certical instruments which are placed on the market from 22 July 2017. 4. Paragraph I shall not apply to ables or spare parts for the repair the resue, the systelling of functionalities or symptolic of companies of the following.	Decisions on the inclusion of materials and components EEE in the lists in America III and IV and on the duration any exemptions shall take into account the availability substitutes and the sociocomonic impact of substitutes Decisions on the duration of any exemptions shall as the account any powerful adverse impacts or innovation Life-cycle divining on the overall impacts of the exemption shall apply, where selvants.
(a) EEE placed on the market before 1 July 2006:	(b) deletion of materials and components of EEE from the list in Annexes III and IV where the conditions set out in poir (a) are no longer fulfilled.
(b) medical devices placed on the market before 22 July 2014;	
(c) in vitro diagnostic medical devices placed on the market before 22 July 2016; (d) monitoring and control instruments placed on the market	 Measures adopted in accordance with point (a) of paragraph 1 shall, for categories 1 to 7, 10 and 11 of Anne 1, 4 a validity period of up to 5 years and, for categories and 9 of Annex 1, a validity period of up to 7 years. The validit
before 22 July 2014:	periods are to be decided on a case-by-case basis and may b renewed.
 industrial monitoring and control instruments placed on the market before 22 July 2017; 	For the exemptions listed in Annex III as at 21 July 2011, th
(f) EEE which benefited from an exemption and which was placed on the market before that exemption expired as far as that specific exemption is concerned.	maximum validity period, which may be renewed, shall, for categories 1 to 7 and 10 of Annex I, be 5 years fror 21 July 2011 and, for categories 8 and 9 of Annex I, 7 year from the relevant dates ladd down in Article 4(3), unless shorter period is specified.
5. Rangyaph I shall not apply to reused spare parts, recovered from EEE placed on the market before 1 July 2006 and used in equipment placed on the market before 1 July 2016, provided that reuse takes place in auditable closed-loop business-to-business return systems, and that the reuse of parts is notified to the consumer.	For the exemptions listed in Annex IV as at 21 July 2011, th maximum validity period, which may be renewed shall be years from the relevant dates laid down in Article 4(3), unless shorter period is specified.
Paragraph 1 shall not apply to the applications listed in Armexes III and IV. Article 5	 An application for granting, renewing or revoking a exemption shall be made to the Commission in accordance with Annex V.
Adaptation of the Annexes to scientific and technical progress	4. The Commission shall:
 For the purposes of adapting Armexes III and IV to scientific and inclinical progress, and in order to achieve the objectives see out in Arricle 1. the Commission shall adopt by means of individual delegated acts in accordance with Article 20 and subject to the conditions that doesn in Articles 21 and 22. 	 (a) acknowledge receipt of an application in writing within 1 days of its receipt. The acknowledgement shall state the dat of receipt of the application;
the following measures: (a) inclusion of materials and components of EEE for specific applications in the lists in Annexes III and IV, provided that	(b) inform the Member States of the application without dela and make the application and any supplementar information supplied by the applicant available to them:
such inclusion does not weaken the environmental and health protection afforded by Regulation (EC) No 1907/2006 and where any of the following conditions is	(c) make a summary of the application available to the publi
fulfilled:	(d) evaluate the application and its justification.
 their elimination or substitution via design changes or materials and components which do not require any of the materials or substances listed in Annex II is scien- tifically or technically impracticable, 	 An application for renewal of an exemption shall be mad no later than 18 months before the exemption expires.
- the reliability of substitutes is not ensured,	The Commission shall decide on an application for renewal
 the total negative environmental, health and consumer safety impacts caused by substitution are likely to outweigh the total environmental, health and 	an exemption no later than 6 months before the expiry date of the existing exemption unless specific circumstances justifi- other deadlines. The existing exemption shall remain vali- until a decision on the renewal application is taken by the

7.2011		N Official Journal of the Europe	an Union	L 174/103
	_	Exemption	Scope and dates of applicability	
	6(a)	Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0.35 % lead by weight		
	6(b)	Lead as an alloying element in aluminium containing up to 0.4 % lead by weight		
	6(c)	Copper alloy containing up to 4 % lead by weight	_	
	7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)		
	7(6)	Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for tele- communications.		
	7(e)-1	Electrical and electronic components containing lead in a glass or censuric other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.		
	7(c)-11	Lead in dielectric ceramic in capacitors for a rated voltage of 125 Y AC or 250 Y DC or higher		
	7(c)-III	Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 Y AC or 250 V DC	Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013	
	8(a)	Cadmitum and its compounds in one shot pellet type thermal cut-offs	Expires on 1 January 2012 and after that date may be used in spare parts for EEE placed on the market before 1 January 2012	
	8(b)	Cadmium and its compounds in electrical contacts		
	9	Heravalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0.75 % by weight in the cooling solution		
	9(b)	Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications		
	Па	Lead used in C-press compliant pin connector systems	May be used in spare parts for EEE placed on the market before 24 September 2010	
	11(b)	Lead used in other than C-press compliant pin connector systems	Expires on 1 January 2013 and after that date may be used in spare parts for EEE placed on the market before 1 January 2013	
	12	Lead as a coating material for the thermal conduction module C-ring	May be used in spare parts for EEE placed on the market before 24 September 2010	
	13(a)	Lead in white glasses used for optical applications		
	13(b)	Cadmium and lead in filter glasses and glasses used for reflectance standards		
	14	lead in solders consisting of more than two elements for the connection between the pins and the package of micropro- cessors with a lead content of more than 80 % and less than 85 % by weight	Expired on 1 January 2011 and after that date may be used in spare parts for EEE placed on the warket before 1 January 2011	